



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D

** : Required Field*

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2020-01-15
Company Unique ID	NL 008751171B01		
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Contact Phone *	Refer to Supplier Comment section	Contact Email *	Refer to Supplier Comment section
Authorized Representative *	Rossana Bonaccorso	Representative Title	ADG MD CHAMPION
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement

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Legal Statement

Supplier Acceptance *	true	Legal Declaration *	Standard
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Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STGB25N36LZAG	T2D2*SZA4A62	A	3068	2020-01-15
	Amount	UoM	Unit type	ST ECOPACK Grade
	1380	mg	Each	ECOPACK 1
Comment	ECOPACK® or ECOPACK® 1 is STMicroelectronics trade name for ROHS compliant devices			

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
1	245	3		
Bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable	Tin (Sn), matte, annealed	Copper Alloy	DM00652460	

Package Designator	Size	Nbr of instances	Shape	
SIP	10.20,9.15,4.50	3	gull wing	
Comment	D2PAK			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-March 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	FALSE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	TRUE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

QueryList : ELV directive : 2000/53/EC amended 2017/2096 _November 2017	
Query	Response
1 - Product(s) meets EU ELV requirements without any exemptions	FALSE
2 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	TRUE
Exemption Id.	Description
8e	Lead in high melting temperature type solders (i.e. lead-based alloys containing 85 % by weight or more lead)

QueryList : California Prop65 list, dated 13th September 2019			
Query			Response
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen			FALSE
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen			TRUE
Substance	amount in product (mg)	Application	ppm in product
Nickel	0.16	Die - Leadframe	114
Lead	4.27	Soft solder	3092
Antimony trioxide	6.98	Mold compound	5058

QueryList : REACH-16th July 2019				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				FALSE
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product
Lead	1000 ppm	4.27	Soft solder	3092
2 - Product(s) does not contain REACH Substances Of Very High Concern in any Embedded article nor Homogeneous Material above the limits per the definition within REACH				FALSE
CategoryLevel_Name	CategoryLevel_Threshold	Amount in Embedded Article / Homogeneous Material (mg)	Application - Article / Homogeneous Material	ppm in Article /Homogeneous Material
Lead	1000 ppm	4.27	Soft solder	955013

Material Composition Declaration :						Mfr Item Name	T2D2*SZA4A62					
note : Substance present with less 0.001mg will not be declared in this document												
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	M-011 Other inorganic materials	11.261	mg	supplier	die	Silicon(Si)	7440-21-3		10.859	mg	964302	7869
				supplier	metallisation	Aluminium(Al)	7429-90-5		0.151	mg	13409	109
				supplier	metallisation	Chromium(Cr)	7440-47-3		0.006	mg	533	4
				supplier	metallisation	Nicke(Ni)	7440-02-0		0.052	mg	4618	38
				supplier	metallisation	Silver(Ag)	7440-22-4		0.018	mg	1598	13
				supplier	Passivation	Silicon nitride(SiN)	12033-89-5		0.036	mg	3197	26
				supplier	passivation	Silicon oxide	7631-86-9		0.053	mg	4706	38
				supplier	polymer coating	Durimide	proprietary		0.086	mg	7637	62
Leadframe	M-004 Copper and its alloys	778.660	mg	supplier	alloy & coating	Copper(Cu)	7440-50-8		777.532	mg	998551	563429
				supplier	alloy & coating	Nicke(Ni)	7440-02-0		0.105	mg	135	76
				supplier	alloy & coating	Iron(Fe)	7439-89-6		0.358	mg	460	259
				supplier	alloy & coating	Iron Phosphide(FeP)	26508-33-8		0.654	mg	840	474
				supplier	alloy & coating	Phosphorus metal	7723-14-0		0.011	mg	14	8
Soft solder	Solder	4.468	mg	SVHC	solder	Lead(Pb)	7439-92-1	7a-Lead in high melting temper	4.267	mg	955013	3092
				supplier	solder	Silver(Ag)	7440-22-4		0.112	mg	25067	81
				supplier	solder	Tin(Sn)	7440-31-5		0.089	mg	19920	64
Bonding wires	M-003 Aluminum and its alloys	1.286	mg	supplier	wire	Aluminium (Al)	7429-90-5		1.286	mg	1000000	932
Bonding wires 2	M-003 Aluminum and its alloys	0.132	mg	supplier	wire	Aluminium (Al)	7429-90-5		0.131	mg	992424	95
				supplier	wire	Magnesium (Mg)	7439-95-4		0.001	mg	7576	1
Encapsulation	M-011 Other inorganic materials	581.704	mg	supplier	mold compound	Silica vitreous	60676-86-0		478.743	mg	823001	346915
				supplier	mold compound	Epoxy Cresol Novolac	29690-82-2		40.719	mg	70000	29507
				supplier	mold compound	Phenol resin	9003-35-4		23.268	mg	40000	16861
				supplier	mold compound	Biphenyl epoxy resin	85954-11-6		17.451	mg	30000	12646
				supplier	mold compound	Antimony trioxide	1309-64-4		6.980	mg	11999	5058
				supplier	mold compound	Brominated epoxy resin	40039-93-8		11.634	mg	20000	8430
				supplier	mold compound	Carbon black	1333-86-4		2.909	mg	5000	2108
Connections coating	Solder	2.489	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		2.489	mg	1000000	1805